Abstracts

Microwave-circuit modeling of high lead-count plastic packages

R.W. Jackson and S. Rakshit. "Microwave-circuit modeling of high lead-count plastic packages." 1997 Transactions on Microwave Theory and Techniques 45.10 (Oct. 1997, Part II [T-MTT] (Special Issue on Interconnects and Packaging)): 1926-1933.

A microwave-circuit model topology for elevated-paddle surface-mount packages is extended to packages with high-lead counts. Features such as irregular lead structures, long wirebonds, smaller pitches, and finite-lead thickness are all examined. The modeling technique is applied to a shrink small-outline package (SSOP-24) with the results compared to measurements of a 25 times size scale model. The circuit model is used to investigate the performance of a matched transition.

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